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ispXPLD[®] 5000MX Device Datasheet

June 2010

Select Devices Discontinued!

Product Change Notifications (PCNs) #09-10 has been issued to discontinue select devices in this data sheet.

The original datasheet pages have not been modified and do not reflect those changes. Please refer to the table below for reference PCN and current product status.

Product Line	Ordering Part Number	Product Status	Reference PCN
LC5256MV	LC5256MV-4F256C	Active / Orderable	
	LC5256MV-4FN256C		
	LC5256MV-5F256C		
	LC5256MV-5FN256C		
	LC5256MV-75F256C		
	LC5256MV-75FN256C		
	LC5256MV-5F256I		
	LC5256MV-5FN256I		
	LC5256MV-75F256I		
	LC5256MV-75FN256I		
LC5256MB	LC5256MB-4F256C	Active / Orderable	
	LC5256MB-4FN256C		
	LC5256MB-5F256C		
	LC5256MB-5FN256C		
	LC5256MB-75F256C		
	LC5256MB-75FN256C		
	LC5256MB-5F256I		
	LC5256MB-5FN256I		
	LC5256MB-75F256I		
	LC5256MB-75FN256I		
LC5256MC	LC5256MC-4F256C	Discontinued	PCN#09-10
	LC5256MC-4FN256C		
	LC5256MC-5F256C		
	LC5256MC-5FN256C		
	LC5256MC-75F256C		
	LC5256MC-75FN256C		
	LC5256MC-5F256I		
	LC5256MC-5FN256I		
	LC5256MC-75F256I		
	LC5256MC-75FN256I		



Product Line	Ordering Part Number	Product Status	Reference PCN	
LC5512MV	LC5512MV-45Q208C	Active / Orderable		
	LC5512MV-45QN208C			
	LC5512MV-75Q208C			
	LC5512MV-75QN208C			
	LC5512MV-75Q208I			
	LC5512MV-75QN208I			
	LC5512MV-45F256C			
	LC5512MV-45FN256C			
	LC5512MV-75F256C			
	LC5512MV-75FN256C			
	LC5512MV-75F256I			
	LC5512MV-75FN256I			
	LC5512MV-45F484C			
	LC5512MV-45FN484C			
	LC5512MV-75F484C			
	LC5512MV-75FN484C			
LC5512MV-75F484I	Discontinued	PCN#09-10		
LC5512MV-75FN484I				
LC5512MB-45Q208C				
LC5512MB-45QN208C				
LC5512MB-75Q208C				
LC5512MB-75QN208C				
LC5512MB-75Q208I				
LC5512MB-75QN208I				
LC5512MB-45F256C			Active / Orderable	
LC5512MB-45FN256C				
LC5512MB-75F256C				
LC5512MB-75FN256C				
LC5512MB-75F256I				
LC5512MB-75FN256I				
LC5512MB-45F484C				
LC5512MB-45FN484C				
LC5512MB-75F484C	Discontinued	PCN#09-10		
LC5512MB-75FN484C				
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LC5512MB-75FN484I				
LC5512MC-45Q208C				
LC5512MC-45QN208C				
LC5512MC-75Q208C				
LC5512MC-75QN208C				
LC5512MC-75Q208I			Discontinued	PCN#09-10
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LC5512MC-75F256C				
LC5512MC-75FN256C				
LC5512MC-75F256I				
LC5512MC-75FN256I				



Product Line	Ordering Part Number	Product Status	Reference PCN
LC5512MC (Cont'd)	LC5512MC-45F484C	Discontinued	PCN#09-10
	LC5512MC-45FN484C		
	LC5512MC-75F484C		
	LC5512MC-75FN484C		
	LC5512MC-75F484I		
	LC5512MC-75FN484I		
LC5768MV	LC5768MV-5F256C	Active / Orderable	
	LC5768MV-5FN256C		
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	LC5768MV-75F256I		
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LC5768MB-75F484C			
LC5768MB-75FN484C			
LC5768MB-75F484I			
LC5768MB-75FN484I			
LC5768MC		LC5768MC-5F256C	Discontinued
	LC5768MC-5FN256C		
	LC5768MC-75F256C		
	LC5768MC-75FN256C		
	LC5768MC-75F256I		
	LC5768MC-75FN256I		
	LC5768MC-5F484C		
	LC5768MC-5FN484C		
	LC5768MC-75F484C		
	LC5768MC-75FN484C		
	LC5768MC-75F484I		
	LC5768MC-75FN484I		



Product Line	Ordering Part Number	Product Status	Reference PCN
LC51024MV	LC51024MV-52F484C	Active / Orderable	
	LC51024MV-52FN484C		
	LC51024MV-75F484C		
	LC51024MV-75FN484C		
	LC51024MV-75F484I		
	LC51024MV-75FN484I		
	LC51024MV-52F672C		
	LC51024MV-52FN672C		
	LC51024MV-75F672C		
	LC51024MV-75FN672C		
	LC51024MV-75F672I		
	LC51024MV-75FN672I		
LC51024MB	LC51024MB-52F484C	Discontinued	PCN#09-10
	LC51024MB-52FN484C		
	LC51024MB-75F484C		
	LC51024MB-75FN484C		
	LC51024MB-75F484I		
	LC51024MB-75FN484I		
	LC51024MB-52F672C		
	LC51024MB-52FN672C		
	LC51024MB-75F672C		
	LC51024MB-75FN672C		
	LC51024MB-75F672I		
	LC51024MB-75FN672I		
LC51024MC	LC51024MC-52F484C	Discontinued	PCN#09-10
	LC51024MC-52FN484C		
	LC51024MC-75F484C		
	LC51024MC-75FN484C		
	LC51024MC-75F484I		
	LC51024MC-75FN484I		
	LC51024MC-52F672C		
	LC51024MC-52FN672C		
	LC51024MC-75F672C		
	LC51024MC-75FN672C		
	LC51024MC-75F672I		
	LC51024MC-75FN672I		

Features

■ Flexible Multi-Function Block (MFB) Architecture

- SuperWIDE™ logic (up to 136 inputs)
- Arithmetic capability
- Single- or Dual-port SRAM
- FIFO
- Ternary CAM

■ sysCLOCK™ PLL Timing Control

- Multiply and divide between 1 and 32
- Clock shifting capability
- External feedback capability

■ sysIO™ Interfaces

- LVCMOS 1.8, 2.5, 3.3V
 - Programmable impedance
 - Hot-socketing
 - Flexible bus-maintenance (Pull-up, pull-down, bus-keeper, or none)
 - Open drain operation
- SSTL 2, 3 (I & II)
- HSTL (I, III, IV)
- PCI 3.3
- GTL+
- LVDS
- LVPECL
- LVTTTL

■ Expanded In-System Programmability (ispXP™)

- Instant-on capability
- Single chip convenience
- In-System Programmable via IEEE 1532 Interface
- Infinitely reconfigurable via IEEE 1532 or sys-CONFIG™ microprocessor interface
- Design security

■ High Speed Operation

- 4.0ns pin-to-pin delays, 300MHz f_{MAX}
- Deterministic timing

■ Low Power Consumption

- Typical static power: 20 to 50mA (1.8V), 30 to 60mA (2.5/3.3V)
- 1.8V core for low dynamic power

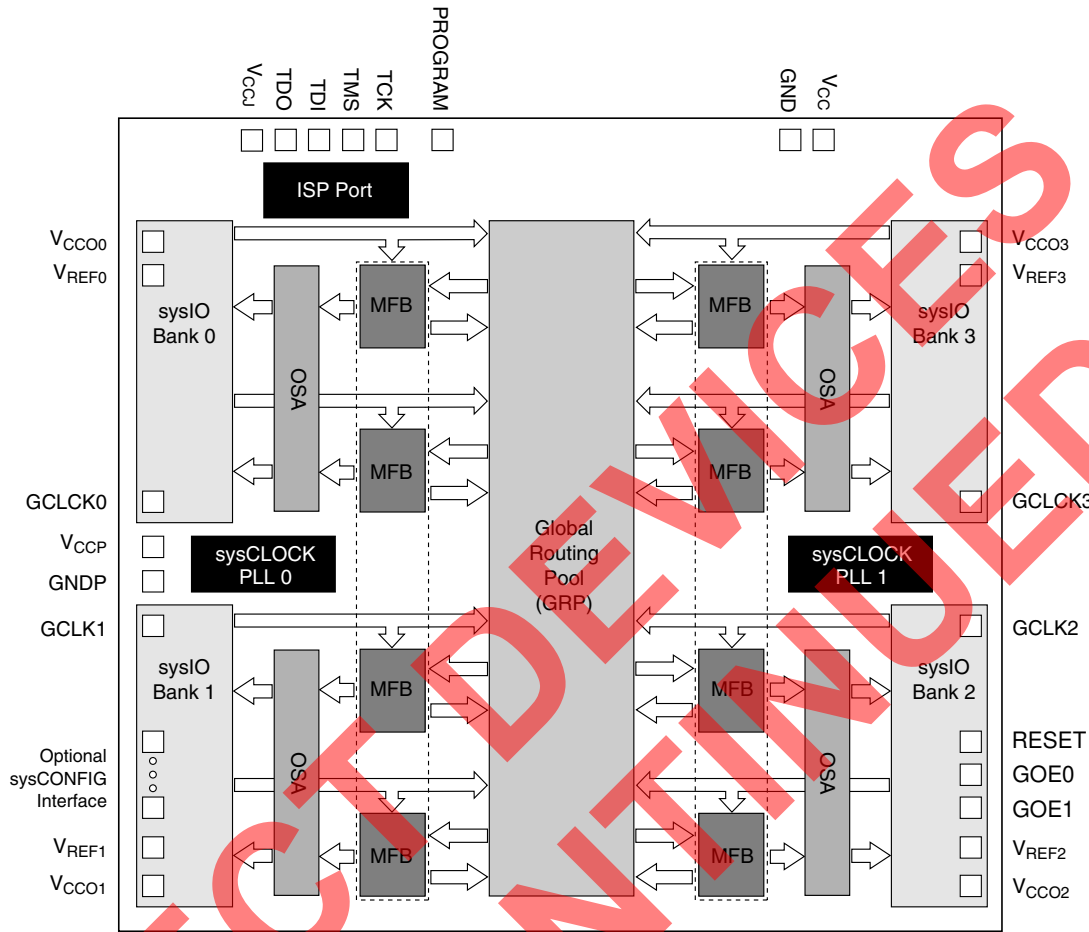
■ Easy System Integration

- 3.3V (5000MV), 2.5V (5000MB) and 1.8V (5000MC) power supply operation
- 5V tolerant I/O for LVCMOS 3.3 and LVTTTL interfaces
- IEEE 1149.1 interface for boundary scan testing
- sysIO quick configuration
- Density migration
- Multiple density and package options
- PQFP and fine pitch BGA packaging
- Lead-free package options

Table 1. ispXPLD 5000MX Family Selection Guide

	ispXPLD 5256MX	ispXPLD 5512MX	ispXPLD 5768MX	ispXPLD 51024MX
Macrocells	256	512	768	1,024
Multi-Function Blocks	8	16	24	32
Maximum RAM Bits	128K	256K	384K	512K
Maximum CAM Bits	48K	96K	144K	192K
sysCLOCK PLLs	2	2	2	2
t_{PD} (Propagation Delay)	4.0ns	4.5ns	5.0ns	5.2ns
t_S (Register Set-up Time)	2.2ns	2.8ns	2.8ns	3.0ns
t_{CO} (Register Clock to Out Time)	2.8ns	3.0ns	3.2ns	3.7ns
f_{MAX} (Maximum Operating Frequency)	300MHz	275MHz	250MHz	250MHz
Functional Gates	75K	150K	225K	300K
I/Os	141	149/193/253	193/317	317/381
Packages	256 fpBGA	208 PQFP 256 fpBGA 484 fpBGA	256 fpBGA 484 fpBGA	484 fpBGA 672 fpBGA

Figure 1. ispXPLD 5000MX Block Diagram



Introduction

The ispXPLD 5000MX family represents a new class of device, referred to as the eXpanded Programmable Logic Devices (XPLDs). These devices extend the capability of Lattice’s popular SuperWIDE ispMACH 5000 architecture by providing flexible memory capability. The family supports single- or dual-port SRAM, FIFO, and ternary CAM operation. Extra logic has also been included to allow efficient implementation of arithmetic functions. In addition, sysCLOCK PLLs and sysIO interfaces provide support for the system-level needs of designers.

The devices provide designers with a convenient one-chip solution that provides logic availability at boot-up, design security, and extreme reconfigurability. The use of advanced process technology provides industry-leading performance with combinatorial propagation delay as low as 4.0ns, 2.8ns clock-to-out delay, 2.2ns set-up time, and operating frequency up to 300MHz. This performance is coupled with low static and dynamic power consumption. The ispXPLD 5000MX architecture provides predictable deterministic timing.

The availability of 3.3, 2.5 and 1.8V versions of these devices along with the flexibility of the sysIO interface helps users meet the challenge of today’s mixed voltage designs. Inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. Boundary scan testability further eases integration into today’s complex systems. A variety of density and package options increase the likelihood of a good fit for a particular application. Table 1 shows the members of the ispXPLD 5000MX family.

Architecture

The ispXPLD 5000MX devices consist of Multi-Function Blocks (MFBs) interconnected with a Global Routing Pool. Signals enter and leave the device via one of four sysIO banks. Figure 1 shows the block diagram of the ispXPLD

5000MX. Incoming signals may connect to the global routing pool or the registers in the MFBs. An Output Sharing Array (OSA) increases the number of I/O available to each MFB, allowing a complete function high-performance access to the I/O. There are four clock pins that drive four global clock nets within the device. Two sysCLOCK PLLs are provided to allow the synthesis of new clocks and control of clock skews.

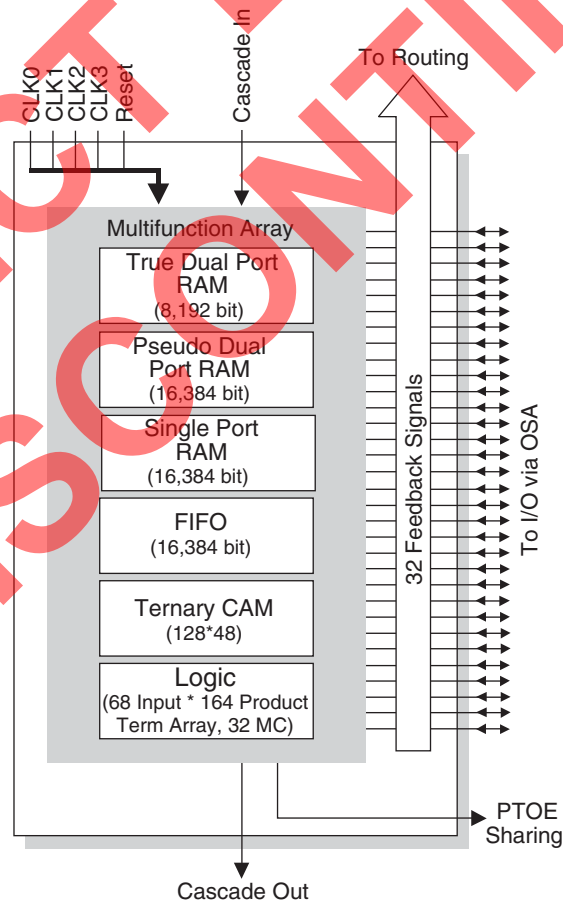
Multi-Function Block (MFB)

Each MFB in the ispXPLD 5000MX architecture can be configured in one of the six following modes. This provides a flexible approach to implementing logic and memory that allows the designer to achieve the mix of functions that are required for a particular design, maximizing resource utilization. The six modes supported by the MFB are:

- SuperWIDE Logic Mode
- True Dual-port SRAM Mode
- Pseudo Dual-port SRAM Mode
- Single-port SRAM Mode
- FIFO Mode
- Ternary CAM Mode

The MFB consists of a multi-function array and associated routing. Depending on the chosen functions the multi-function array uses up to 68 inputs from the GRP and the four global clock and reset signals. The array outputs data along with certain control functions to the macrocells. Output signals can be routed internally for use elsewhere in the device and to the sysIO banks for output. Figure 2 shows the block diagram of the MFB. The various configurations are described in more detail in the following sections.

Figure 2. MFB Block Diagram



Cascading For Wide Operation

In several modes it is possible to cascade adjacent MFBs to support wider operation. Table 2 details the different cascading options. There are chains of MFBs in each device which determine those MFBs that are adjacent for the purposes of cascading. Table 3 indicates these chains. The ispXPLD 5000MX design tools automatically cascade blocks if required by a particular design.

Table 2. Cascading Modes For Wide Support

Mode	Cascading Function
Logic	Input Width. Allows two MFBs to act as a 136-input block.
	Arithmetic. Allow the carry chain to pass between two MFBs.
FIFO	Memory Width Expansion. Allows MFBs to be cascaded for greater width support.
CAM	Memory Width Expansion. Allows up to four MFBs to be cascaded for greater width support.

Table 3. MFB Cascade Chain

Device	MFBs in Cascade Chain
ispXPLD 5256MX	A → B → C → D
	H → G → F → E
ispXPLD 5512MX	A → B → C → D → E → F → G → H
	P → O → N → M → L → K → J → I
ispXPLD 5768MX	D → C → B → A → X → W → V → U → T → S → R → Q
	E → F → G → H → I → J → K → L → M → N → O → P
ispXPLD 51024MX	H → G → F → E → D → C → B → A → AF → AE → AD → AC → AB → AA → Z → Y
	I → J → K → L → M → N → O → P → Q → R → S → T → U → V → W → X

SuperWIDE Logic Mode

In logic mode, each MFB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and four control product terms. The MFB has 68 inputs from the Global Routing Pool, which are available in both true and complement form for every product term. It is also possible to cascade adjacent MFBs to create a block with 136 inputs. The four control product terms are used for shared reset, clock, clock enable, and output enable functions. Figure 3 shows the overall structure of the MFB in logic mode while Figure 4 provides a more detailed view from the perspective of a macrocell slice.

Figure 3. MFB in SuperWIDE Logic Mode†

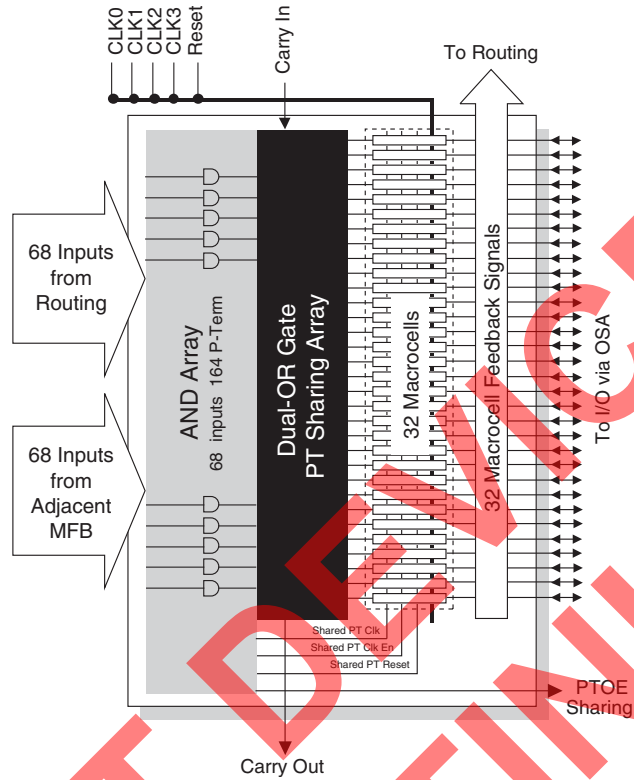
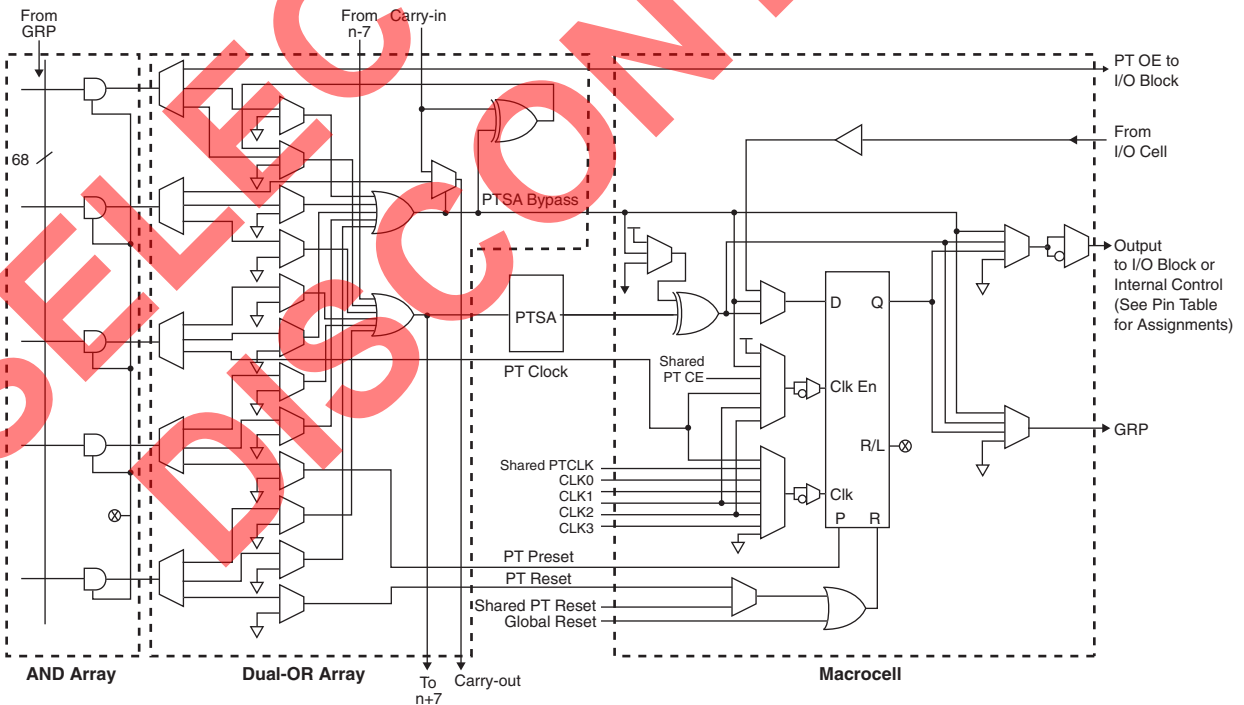


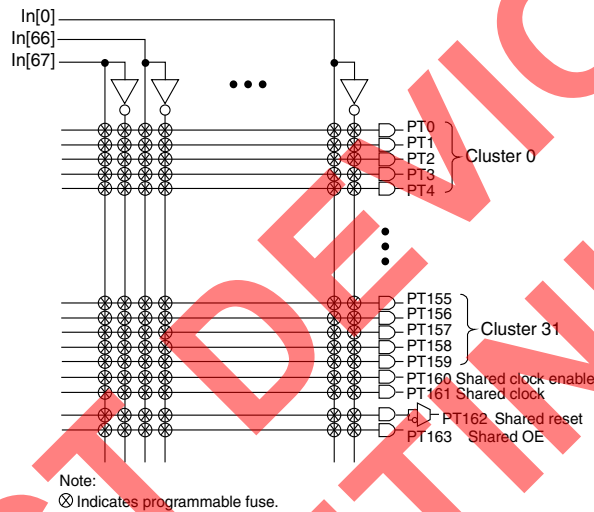
Figure 4. Macrocell Slice in Logic Mode AND-Array



AND-Array

The programmable AND-Array consists of 68 inputs and 164 output product terms. The 68 inputs from the GRP are used to form 136 lines in the AND-Array (true and complement of the inputs). Each line in the array can be connected to any of the 164 output product terms via a wired AND. Each of the 160 logic product terms feed the Dual-OR Array with the remaining four control product terms feeding the Shared PT Clock, Shared PT Clock Enable, Shared PT Reset and Shared PT OE. Starting with PT0 sets of five product terms form product term clusters. There is one product term cluster for every macrocell in the MFB. In addition to the four control product terms, the first, third, fourth and fifth product terms of each cluster can be used as a PTOE, PT Clock, PT Preset and PT Reset, respectively. Figure 5 is a graphical representation of the AND-Array.

Figure 5. AND Array

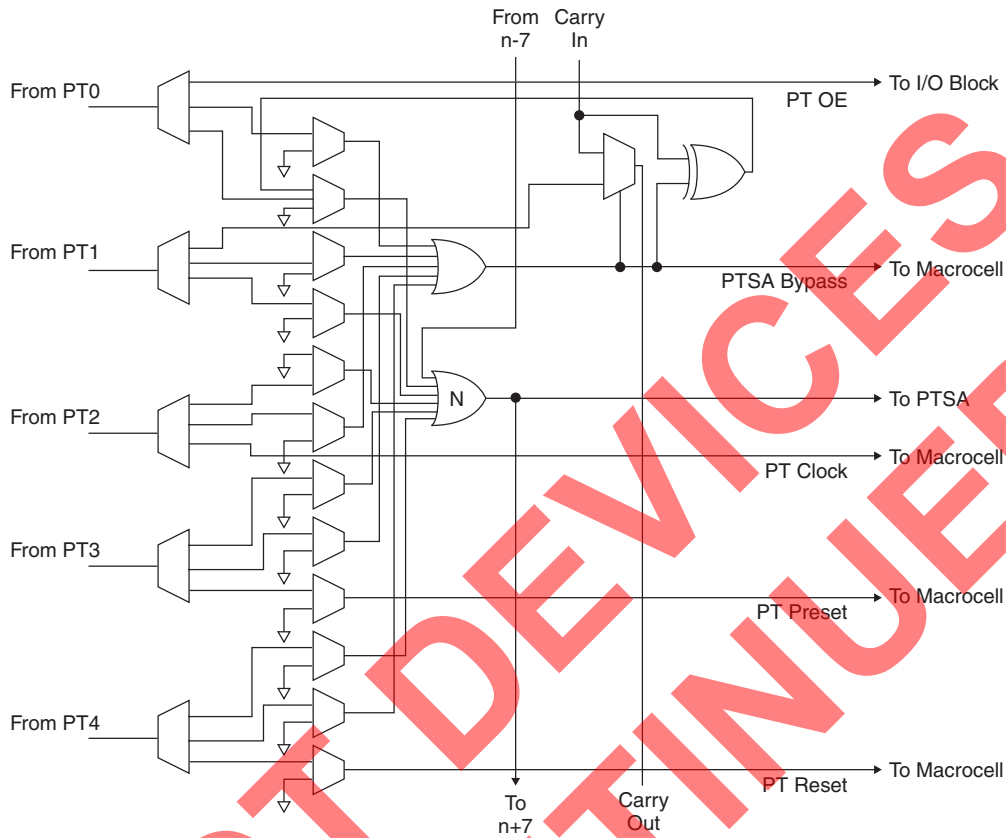


Dual-OR Array (Including Arithmetic Support)

The Dual-OR Array consists of 64 OR gates. There are two OR gates per macrocell in the MFB. These OR gates are referred to as the Expandable PTSA OR gate and the PTSA-Bypass OR gate. The PTSA-Bypass OR gate receives its five inputs from the combination of product terms associated with the product term cluster. The PTSA-Bypass OR gate feeds the macrocell directly for fast narrow logic. The Expandable PTSA OR gate receives five inputs from the combination of product terms associated with the product term cluster. It also receives an additional input from the Expanded PTSA OR gate of the N-7 macrocell, where N is the number of the macrocell associated with the current OR gate. The Expandable PTSA OR gate feeds the PTSA for sharing with other product terms and the N+7 Expandable PTSA OR gate. This allows cascading of multiple OR gates for wide functions. There is a small timing adder for each level of expansion. Figure 6 is a graphical representation of the Dual-OR Array.

The Dual-OR PT sharing array also contains logic to aid in the efficient implementation of arithmetic functions. This logic takes Carry In and allows the generation of Carry Out along with a SUM signal. Subtractors can be implemented using the two's complement method. Carry is propagated from macrocells 0 to macrocell 31. Macrocell zero can have its carry input connected to the carry output of macrocell 31 in an adjacent MFB or it can be set to zero or one. If a macrocell is not used in an arithmetic function carry can bypass it. The carry chain flows is the same as that for PT cascading.

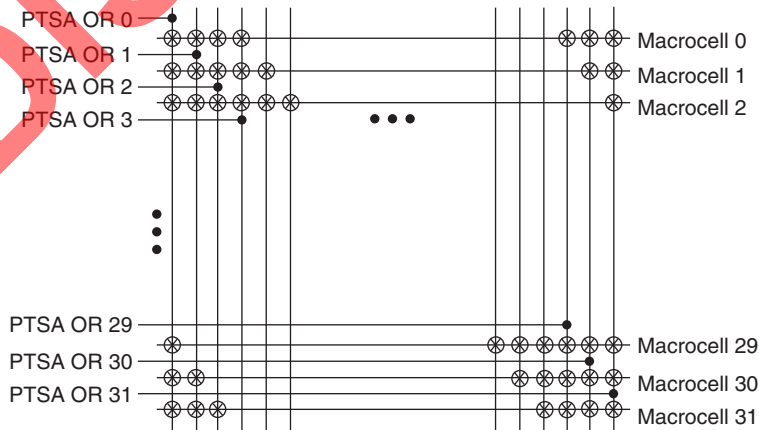
Figure 6. Dual-OR PT Sharing Array



Product Term Sharing Array

The Product Term Sharing Array (PTSA) consists of 32 inputs from the Dual-OR Array (Expandable PTSA OR) and 32 outputs directly to the macrocells. Each output is the OR term of any combination of the seven Expandable PTSA OR terms connected to that output. Every Nth macrocell is connected to N-3, N-2, N-1, N, N+1, N+2 and N+3 PTSA OR terms via a programmable connection. This wraps around the logic, for example, Macrocell 0 gets its logic from 29, 30, 31, 0, 1, 2, 3. The Expandable PTSA OR used in conjunction with the PTSA allows wide functions to be implemented easily and efficiently. Without using the Expandable PTSA OR capability, the greatest number of product terms that can be included in a single function with one pass of delay is 35. Up to 160 product terms can be included in a single function through the use of the expandable PTSA OR capability. Figure 7 shows the graphical representation of the PTSA.

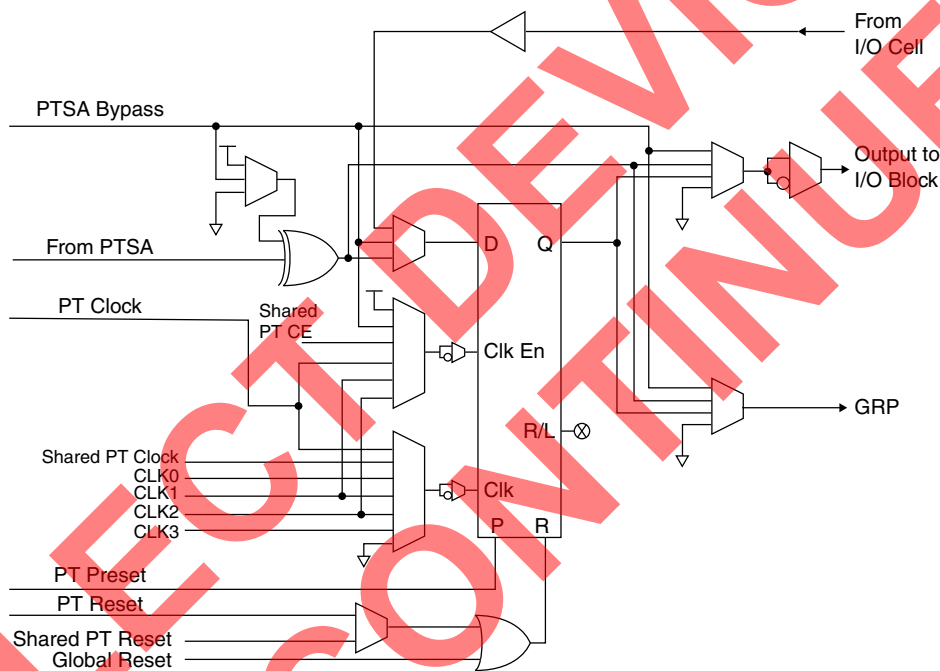
Figure 7. Product Term Sharing Array (PTSA)



Macrocell

The 32 registered macrocells in the MFB are driven by the 32 outputs from the PTSA or the PTSA bypass. Each macrocell contains a programmable XOR gate, a programmable register/latch flip-flop and the necessary clocks and control logic to allow combinatorial or registered operation. All macrocells have an output that feeds the GRP. Selected macrocells have an additional output that feeds the OSA and hence I/Os. This dual or concurrent output capability from the macrocell gives efficient use of the hardware resources. One output can be a registered function for example, while the other output can be an unrelated combinatorial function. A direct register input from the I/O cell facilitates efficient use of the macrocell to construct high-speed input registers. Macrocell registers can be clocked from one of several global or product term clocks available on the device. A global and product term clock enable is also provided, eliminating the need to gate the clock to the macrocell registers directly. Reset and preset for the macrocell register is provided from both global and product term signals. The macrocell register can be programmed to operate as a D-type register or a D-type latch. Figure 8 is a graphical representation of the macrocell.

Figure 8. Macrocell



Memory Modes

The ispXPLD 5000MX architecture allows the MFB to be configured as a variety of memory blocks as detailed in Table 4. The remainder of this section details operation of each of the memory modes. Additional information regarding the memory modes can also be found in TN1030, [Using Memory in ispXPLD 5000MX Devices](#).

Table 4. MFB Memory Configuration

Memory Mode	Max. Configuration Size ¹
Dual-port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 8 512 x 16
Single-port, Pseudo Dual Port, FIFO	16,384 x1 8,192 x 2 4,096 x 4 2,048 x 8 1,024 x 16 512 x 32
CAM	128 x 48

1. Smaller configurations are possible.

Input and Output

The data input and control signals to a MFB in memory mode are generated from inputs from the routing. Data signals are only available in the true non-inverted format. True or complemented versions of the inputs are available for generating the control signals. Data and flag outputs are fed from the MFB to the GRP and OSA. Unused inputs and outputs are not accessible in memory mode.

ROM Operation

In each of the memory modes it is possible to specify the power-on state of each bit in the memory array. This allows the memory to be used as ROM if desired.

Increased Depth And Width

Designs that require a memory depth or width that is greater than that support by a single MFB can be supported by cascading multiple blocks. For dual port, single port, and pseudo dual port modes additional width is easily provided by sharing address lines. Additional depth is supported by multiplexing the RAM output. For FIFO and CAM modes additional width is supported through the cascading of MFBs.

The Lattice design tools automatically combine blocks to support the memory size specified in the user's design.

Bus Size Matching

All of the memory modes apart from CAM mode support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies this mapping scheme applies to each port.

True Dual-Port SRAM Mode

In Dual-Port SRAM Mode the multi-function array is configured as a dual port SRAM. In this mode two independent read/write ports access the same 8,192-bits of memory. Data widths of 1, 2, 4, 8, and 16 are supported by the MFB. Figure 9 shows the block diagram of the dual port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Resets are asynchronous. All inputs on the same port share the same clock, clock enable, and reset selections. All outputs on the same port share the same clock, clock enable, and reset selections. Selections may be made independently between both inputs and outputs and ports. Table 5 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 9. Dual-Port SRAM Block Diagram

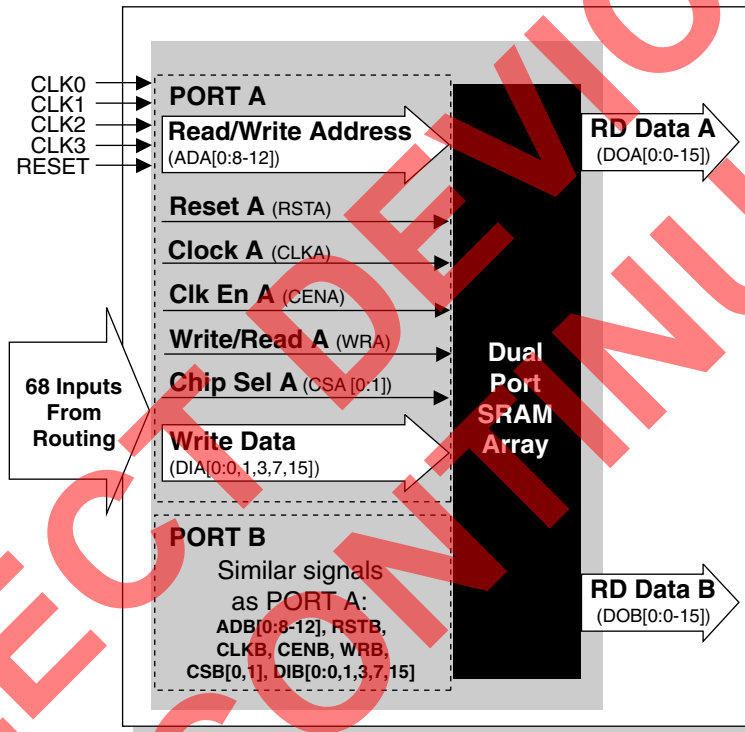


Table 5. Register Clock, Clock Enable, and Reset in Dual-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/Write, and Chip Select	Clock	CLKA (CLKB) or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	CENA (CENB) or one of the global clocks (CLK1 - CLK 2). The selected signal can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RSTA (RSTB). RSTA (RSTB) can be inverted is desired.

Pseudo Dual-Port SRAM Mode

In Pseudo Dual-Port SRAM Mode the multi-function array is configured as a SRAM with an independent read and write ports that access the same 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 10 shows the block diagram of the Pseudo Dual-Port SRAM.

Write data, write address, chip select and write enable signals are always synchronous (registered). The read data and read address signals can be synchronous or asynchronous. Reset is asynchronous. All write signals share the same clock, and clock enable. All read signals share the same clock and clock enable. Reset is shared by both read and write signals. Table 6 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 10. Pseudo Dual-Port SRAM Block Diagram

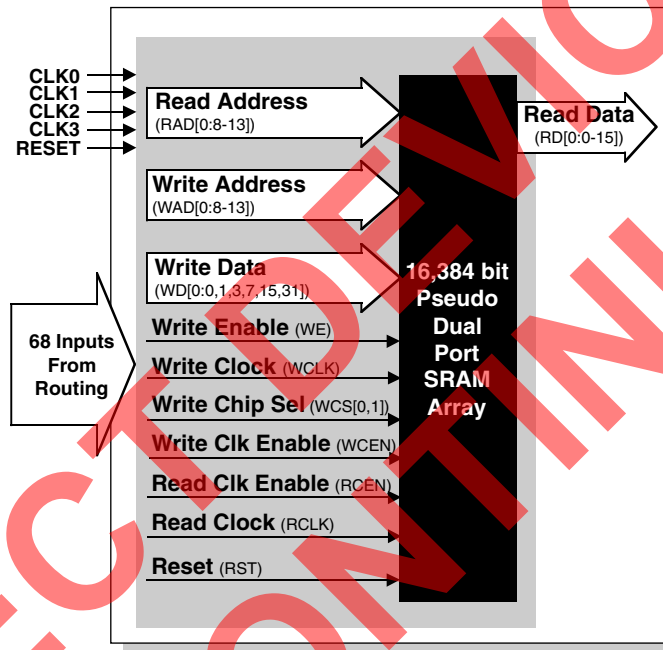


Table 6. Register Clock, Clock Enable, and Reset in Pseudo Dual-Port SRAM Mode

Register	Input	Source
Write Address, Write Data, Write Enable, and Write Chip Select	Clock	WCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	WCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.
Read Data and Read Address	Clock	RCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	RCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.

Single-Port SRAM Mode

In Single-Port SRAM Mode the multi-function array is configured as a single-port SRAM. In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 11 shows the block diagram of the single-port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Reset is asynchronous. All signals share a common clock, clock enable, and reset. Table 7 shows the possible sources for the clock, clock enable and reset signals.

Figure 11. Single-Port SRAM Block Diagram

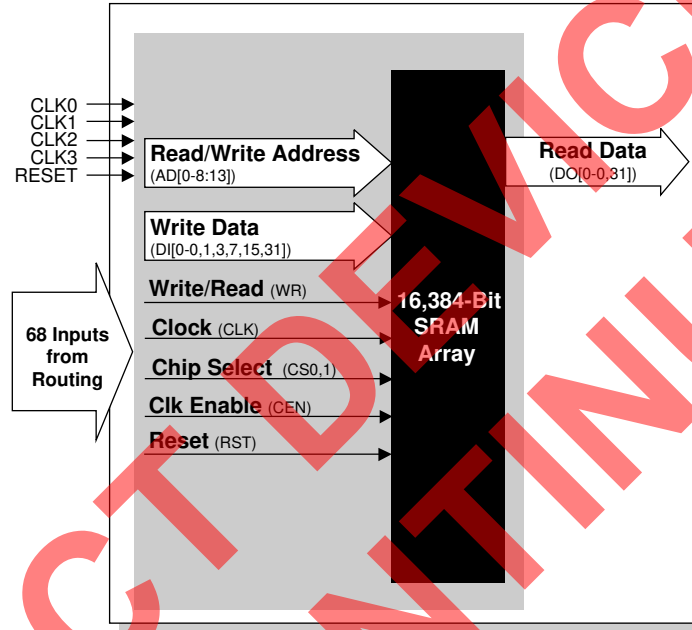


Table 7. Register Clock, Clock Enable, and Reset in Single-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/Write, and Chip Select	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	CEN or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

FIFO Mode

In FIFO Mode the multi-function array is configured as a FIFO (First In First Out) buffer with built in control. The read and write clocks can be different or the same dependent on the application. Four flags show the status of the FIFO; Full, Empty, Almost Full, and Almost Empty. The thresholds for Full, Almost full and Almost empty are programmable by the user. It is possible to reset the read pointer, allowing support of frame retransmit in communications applications. If desired, the block can be used in show ahead mode allowing the early reading of the next read address.

In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 12 shows the block diagram of the FIFO.

Write data, write enable, flag outputs and read enable are synchronous. The Write Data, Almost Full and Full share the same clock and clock enables. Read outputs are synchronous although these can be configured in look ahead mode. The Read Data, Empty and Almost Empty signals share the same clock and clock enables. Reset is shared by all signals. Table 8 shows the possible sources for the clock, clock enable and reset signals for the various registers.

Figure 12. FIFO Block Diagram

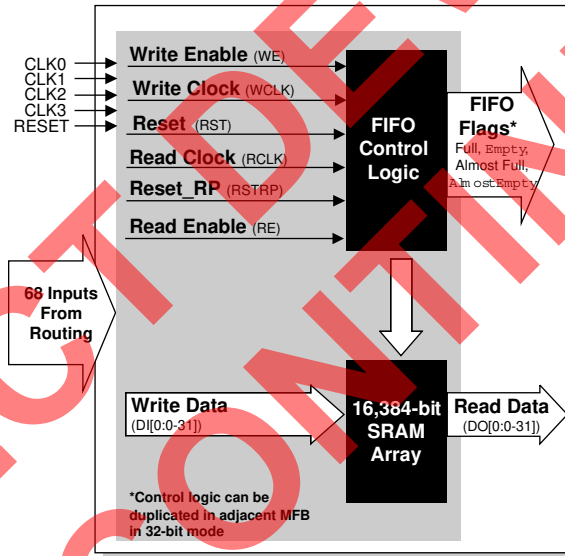


Table 8. Register Clocks, Clock Enables, and Initialization in FIFO Mode

Register	Input	Source
Write Data, Write Enable	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	N/A
Full and Almost Full Flags	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.
Read Data, Empty and Almost Empty Flags	Clock	RCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	RE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

CAM Mode

In CAM Mode the multi-function array is configured as a Ternary Content Addressable Memory (CAM). CAM behaves like a reverse memory where the input is data and the output is an address. It can be used to perform a variety of high-performance look-up functions. As such, CAM has two modes of operation. In write or update mode the CAM behaves as a RAM and data is written to the supplied address. In read or compare operations data is supplied to the CAM and if this matches any of the data in the array the Match and Multiple Match (if there is more than one match) flags are set to true and the lowest address with matching data is output. The CAM contains 128 entries of 48 bits. Figure 13 shows the block diagram of the CAM.

To further enhance the flexibility of the CAM a mask register is available. If enabled during updates, bits corresponding with those set to 1 in the mask register are not updated. If enabled during compare operations, bits corresponding to those set to 1 in the mask register are not included in the compare. A write don't care signal allows don't cares to be programmed into the CAM if desired. Like other write operations the mask register controls this.

The write/comp data, write address, write enable, write chip select, and write don't care signals are synchronous. The CAM Output signals, match flag, and multimatch flag can be synchronous or asynchronous. The Enable mask register input is not latched but must meet setup and hold times relative to the write clock. All inputs must use the same clock and clock enable signals. All outputs must use the same clock and clock enable signals. Reset is common for both inputs and outputs. Table 9 shows the allowable sources for clock, clock enable, and reset for the various CAM registers.

Figure 13. CAM Mode

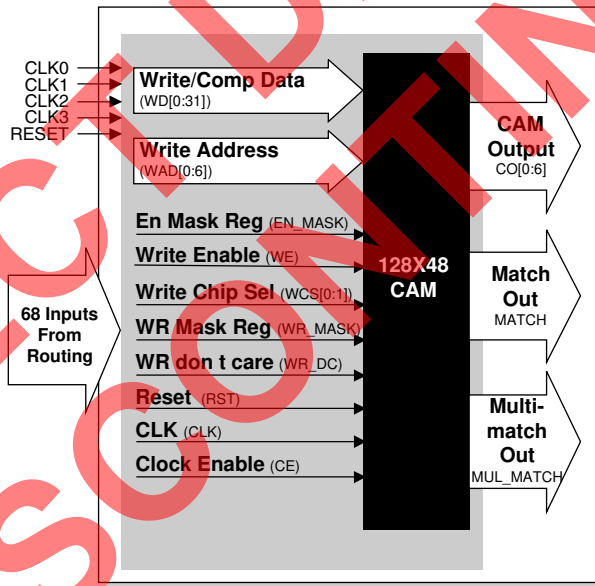


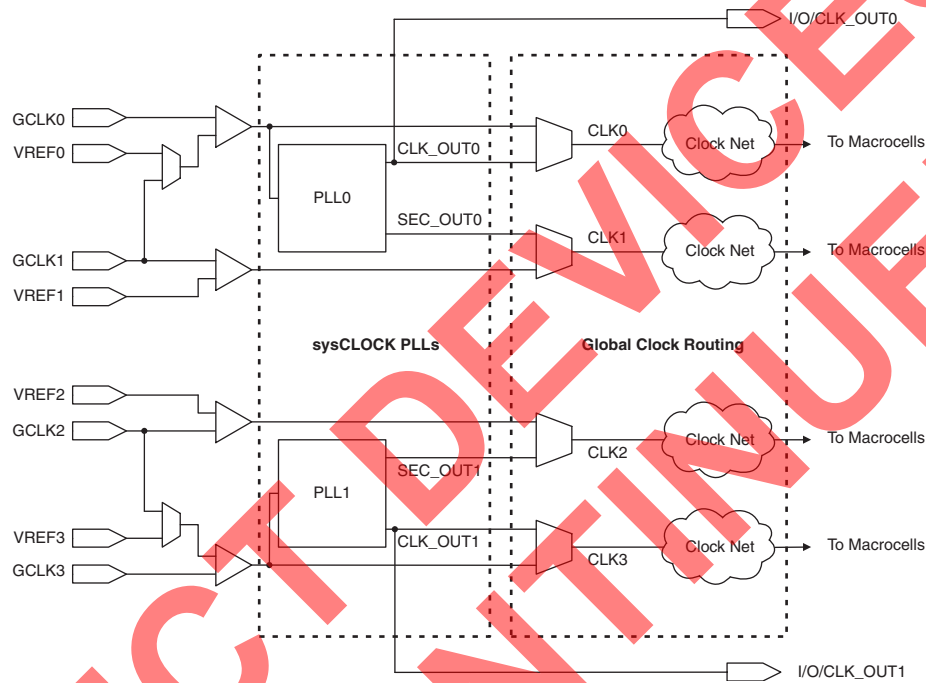
Table 9. Register Clocks, Clock Enables, and Initialization in CAM Mode

Register	Input	Source
Write data, Write address, Enable mask register, Write enable, write chip select, and write don't care, CAM Output, Match, and Multimatch	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired

Clock Distribution

The ispXPLD 5000MX family has four dedicated clock input pins: GCLK0-GCLK3. GCLK0 and GCLK3 can be routed through a PLL circuit or routed directly to the internal clock nets. The internal clock nets (CLK0-CLK3) are directly related to the dedicated clock pins (see Secondary Clock Divider exception when using the sysCLOCK circuit). These feed the registers in the MFBs. Note at each register there is the option of inverting the clock if required. Figure 14 shows the clock distribution network.

Figure 14. Clock Distribution Network



sysCLOCK PLL

The sysCLOCK PLL circuitry consists of Phase-Lock Loops (PLLs) and the various dividers, reset and feedback signals associated with the PLLs. This feature gives the user the ability to synthesize clock frequencies and generate multiple clock signals for routing within the device. Furthermore, it can generate clock signals that are de-skewed either at the board level or the device level.

The ispXPLD 5000MX devices provide two PLL circuits. PLL0 receives its clock inputs from GCLK 0 and provides outputs to CLK 0 (CLK 1 when using the secondary clock). PLL1 operates with signals from GCLK 3 and CLK 3 (CLK 2 when using the secondary clock). The optional outputs CLK_OUT can be routed to an I/O pin. The optional PLL_LOCK output is routed into the GRP. The optional input PLL_RST can be routed either from the GRP or directly from an I/O pin. The optional PLL_FBK into can be routed directly from a pin. Figure 15 shows the ispXPLD 5000MX PLL block diagram. Figure 16 shows the connection of optional inputs and outputs.

Figure 15. PLL Block Diagram

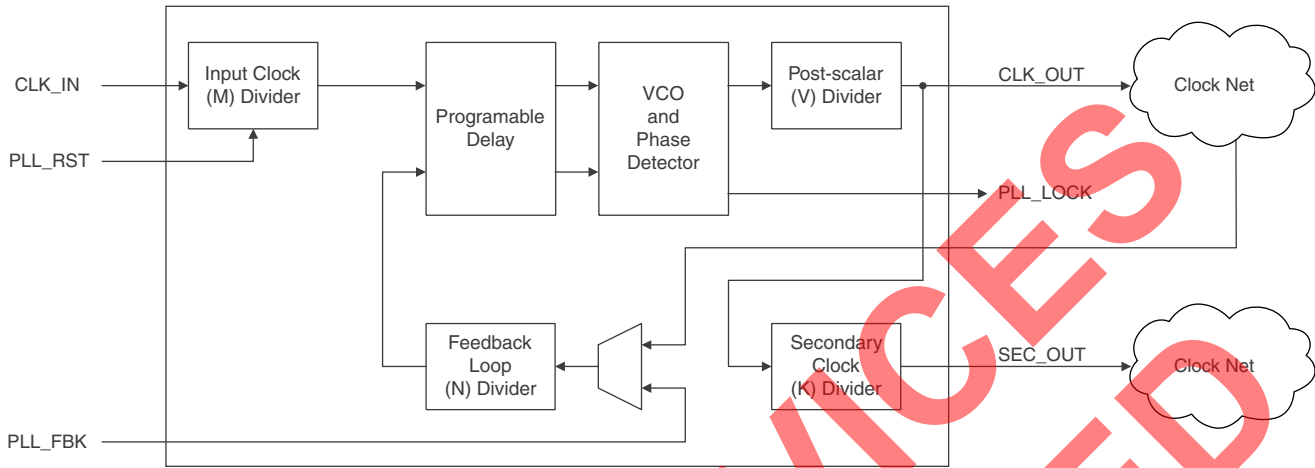
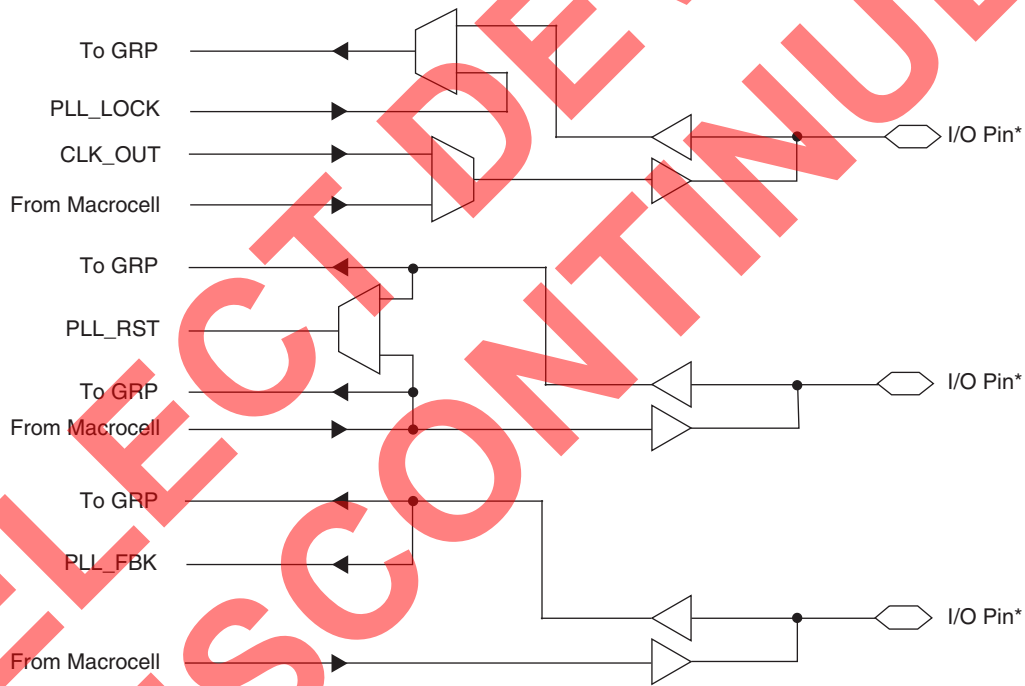


Figure 16. Connection of Optional PLL Inputs and Outputs



*See pinout table for details

In order to facilitate the multiply and divide capabilities of the PLL, each PLL has dividers associated with it: M, N and K. The M divider is used to divide the clock signal, while the N divider is used to multiply the clock signal. The K divider is only used when a secondary clock output is needed. This divider divides the primary clock output and feeds to a separate global clock net. The V divider is used to provide lower frequency output clocks, while maintaining a stable, high frequency output from the PLL's VCO circuit. The PLL also has a delay feature that allows the output clock to be advanced or delayed to improve set-up and clock-to-out times for better performance. For more information on the PLL, please refer to TN1003, [sysCLOCK PLL Usage Guide for ispXPGA, ispGDX2, ispXPLD and ispMACH 5000VG Devices](#).

Output Sharing Array (OSA)

A number of I/O pads are available in each sysIO bank to route the selected number of macrocells from the MFB outputs directly to the I/O pads in logic mode. In the ispXPLD 5000MX, the large number of inputs and PTs to the MFB as well as the presence of the PTSA can cover most routing flexibility of signals to I/O cells. The Output Sharing Array gives additional routing capability and I/O access to an MFB when a wide output function takes up the whole MFB and cannot be easily divided across multiple MFBs. By using the OSA, the wide output function, such as 32-bit FIFO, can have all of its output signals from the one MFB routed to I/O cells. In a given I/O block, the wide output functions must share the I/O pads with other logic functions.

The OSA bypass option routes the MFB signal directly to the I/O cell, allowing a direct connection to the I/O cell. The logic functions use the option to provide faster speed to the outputs. The Logic Signal Connection tables list the OSA bypass as the primary macrocell and OSA options as alternate macrocells. Similarly, the Alternate Input listing in the table shows the alternate macrocell input connection for a given I/O pin. Figure 17 shows the alternate macrocell connections in an I/O cell.

sysIO Banks

The ispXPLD 5000MX devices are divided into four sysIO banks, consisting of multiple I/O cells, where each bank is capable of supporting 16 different I/O standards. Each sysIO bank has its own I/O voltage (V_{CCO}) and reference voltage (V_{REF}) resources allowing complete independence from the others.

I/O Cell

The I/O cell of the ispXPLD 5000MX devices contains an output enable (OE) MUX, a programmable tri-state output buffer, a programmable input buffer, and programmable bus-maintenance circuitry.

The I/O cell receives inputs from its associated macrocells and the device pin. The I/O cell has a feedback line to its associated macrocells and a direct path to GRP. The output enable (OE) MUX selects the OE signal per I/O cell. The inputs to the OE MUX are the four global PTOE signals, PTOE and the two GOE signals. The OE MUX also has the ability to choose either the true or inverse of each of these signals. The output of the OE MUX goes through a logical AND with the TOE signal to allow easy tri-stating of the outputs for testing purposes. The MFBs are grouped into segments of four for the purpose of generating Shared PTOE signals. Each Shared PTOE signal is derived from PT 163 from one of the four MFBs. Table 10 shows the segments. The PTOE signal is derived from the first product term in each macrocell cluster, which is directly routed to the OE MUX. Therefore, every I/O cell can have a different OE signal. Figure 17 is a graphical representation of the I/O cell.

Figure 17. I/O Cell



Table 10. Shared PTOE Segments

Device	MFBs Associated With Segments
ispXPLD 5256MX	(A, B, C, D) (E, F, G, H)
ispXPLD 5512MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P)
ispXPLD 5768MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z)
ispXPLD 51024MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z) (Y, Z, AA, AB) (AC, AD, AE, AF)

sysIO Standards

Each I/O within a bank is individually configurable based on the V_{CCO} and V_{REF} settings. Some standards also require the use of an external termination voltage. Table 12 lists the sysIO standards with the typical values for V_{CCO} , V_{REF} and V_{TT} . For more information on the sysIO capability, refer to TN1000, [sysIO Usage Guidelines for Lattice Devices](#).

Table 11. Number of I/Os per Bank

Device	Maximum Number of I/Os per Bank (n)
ispXPLD 5256MX	36
ispXPLD 5512MX	68
ispXPLD 5768MX	96
ispXPLD 51024MX	96

Table 12. ispXPLD 5000MX Supported I/O Standards

sysIO Standard	Nominal V_{CCO}	Nominal V_{REF}	Nominal V_{TT}
LVTTL	3.3V	N/A	N/A
LVC MOS-3.3	3.3V	N/A	N/A
LVC MOS-2.5	2.5V	N/A	N/A
LVC MOS-1.8	1.8V	N/A	N/A
PCI 3.3V	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I & II	3.3V	1.5V	1.5V
SSTL2, Class I & II	2.5V	1.25V	1.25V
CTT 3.3	3.3V	1.5V	1.5V
CTT 2.5	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	0.75V
HSTL, Class IV	1.5V	0.9V	0.75V
GTL+	N/A	1.0V	1.5V
LVPECL, Differential	2.5V, 3.3V	N/A	N/A
LVDS	2.5V, 3.3V	N/A	N/A

Table 13. Differential Interface Standard Support¹

		sysIO Buffer
LVDS	Driver	Supported
	Receiver	Supported with standard termination
LVPECL	Driver	Supported with external resistor network
	Receiver	Supported with termination

1. For more information, refer to TN1000 – [sysIO Usage Guidelines for Lattice Devices](#).

Control, Clock, sysCONFIG and JTAG Signals

Global clock pins support the same sysIO standards as general purpose I/O. When required the V_{REF} signal is derived from the adjacent bank. When differential standards are supported two adjacent clock pins are paired to form the input. The TOE, PROGRAM, CFG0 and DONE pins of the ispXPLD 5000MX device are the only pins that do not have sysIO capabilities. The JTAG TAP pins support only LVC MOS 3.3, 2.5 and 1.8V standards. The voltage is controlled by V_{CCJ} . These pins only support the LVTTL and LVC MOS standards applicable to the power supply voltage of the device. The global reset global output enable pins are associated with Bank 2 and support all of the sysIO standards.

Hotsocketing

The I/O on the ispXPLD 5000MX devices are well suited for those applications that require hot socketing capability, when configured as LVC MOS or LVTTL. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Programmable Drive Strength

The drive strength of I/Os that are programmed as LVC MOS is tightly controlled and can be programmed to a variety of different values. Thus the impedance an output driver can be closely match to the characteristic impedance of the line it is driving. This allows users to eliminate the need for external series termination resistors.

Programmable Slew Rate

The slew rate of outputs is carefully controlled. When outputs are configured as LVCMOS the devices support two slew rates. This allows system noise and performance to be balanced in a design.

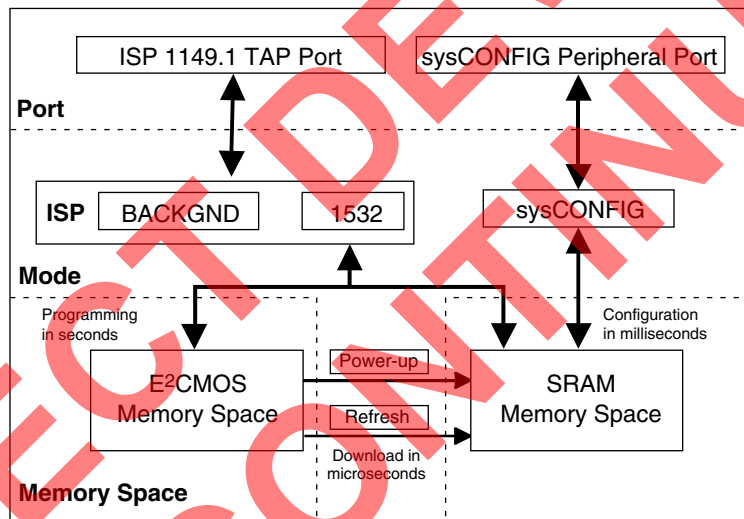
Programmable Bus-Maintenance

All general-purpose inputs have programmable bus maintenance circuitry. These are intended to maintain a valid logic level into a device when driving devices go into the tri-state mode. Four options are available for users: pull-up, pull-down, bus-keeper, or nothing.

Expanded In-System Programmability (ispXP)

The ispXPLD 5000MX family utilizes a combination of EEPROM non-volatile cells and SRAM technology to deliver a logic solution that provides “instant-on” at power-up, a convenient single chip solution, and the capability for infinite reconfiguration. A non-volatile array distributed within the device stores the device configuration. At power-up this information is transferred in a massively parallel fashion into SRAM bits that control the operation of the device. Figure 18 shows the different ports and modes that are used in the configuration and programming of the ispXPLD 5000MX devices.

Figure 18. ispXP Block Diagram



IEEE 1532 ISP

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispXPLD 5000MX devices provide in-system programmability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The IEEE1532 programming interface allows programming of either the non-volatile array or reconfiguration of the SRAM bits.

The ispXPLD 5000MX devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispXPLD 5000MX devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispXPLD 5000MX devices during the testing of a circuit board.

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, [ispXP Configuration Usage Guidelines](#).

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 [Power Estimation in ispXPLD 5000MX Devices](#).

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.